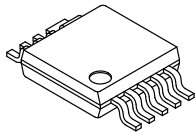


# MECHANICAL CASE OUTLINE

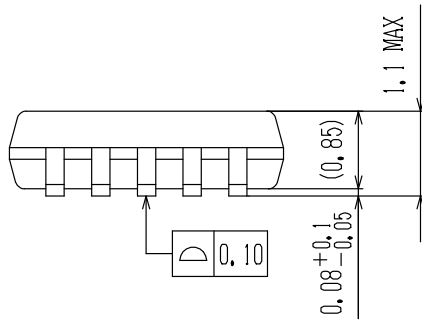
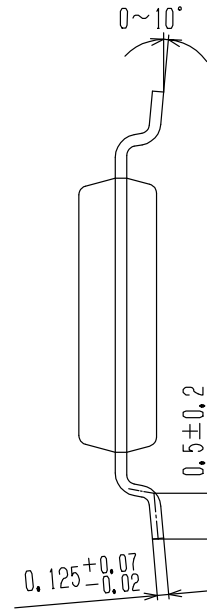
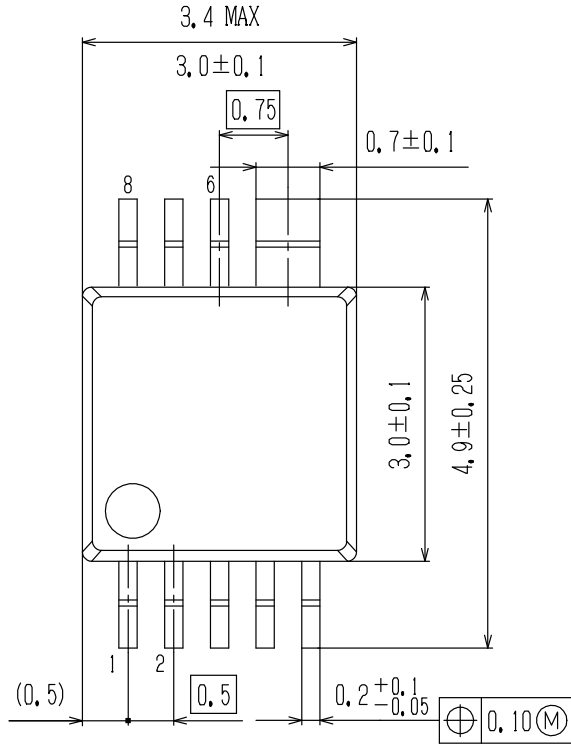
## PACKAGE DIMENSIONS

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**HMSOP8 (150mil)**  
**CASE 846AF**  
**ISSUE O**

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